Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A method for producing an assembly of substrates comprising:

dispensing a liquid polymeric material on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate, at least one of said conducting surfaces having solder deposited thereon,

placing the first substrate on the second substrate such that the liquid polymeric is disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate so that the liquid polymeric material flows towards the edges of the first substrate and the second substrate;

contacting the conducting surface on the first substrate and the conducting surface on the second substrate and melting the solder to form ~~an~~ a solder joint between said conducting surfaces; and

curing the liquid polymeric material, wherein said solder joint is formed before said polymer hardens.

Claim 2 (canceled).

Claim 3 (original): The method of Claim 1 wherein the liquid polymeric material is dispensed on dies present on the first or second substrate.

Claim 4 (original): The method of Claim 1 wherein at least one of the substrates has a planar surface area of at least about 36 sq. inches.

Claim 5 (original): The method of Claim 1 wherein said conducting surface of said first planar substrate includes first conductive pads, and said conducting surface of said second planar

substrate includes second conductive pads and solder bumps disposed on said second conductive pads.

Claim 6 (original): The method of Claim 5 wherein said solder bumps comprise a solder material fluxing agent.

Claim 7 (original): The method of Claim 6 wherein said liquid polymeric material comprises a polymer fluxing agent.

Claim 8 (original): The method of Claim 1 wherein said liquid polymeric material comprises a polymer fluxing agent.

Claim 9 (original): The method of Claim 5 wherein said solder bumps includes no solder material fluxing agent and said liquid polymeric material comprises a polymer fluxing agent.

Claim 10 (previously presented): The method of Claim 7 wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid.

Claim 11 (original): The method of Claim 9 wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid.

Claim 12 (original): The method of Claim 10 wherein said beta phenylacid is selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.

Claim 13 (original): The method of Claim 11 wherein said beta phenylacid is selected from the group consisting of beta phenylacetic acid, beta phenylacrylic acid, beta phenylcrotonic acid, and mixtures thereof.

Claim 14 (previously presented): A method for producing an assembly of substrates comprising:

dispensing a liquid polymeric material on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate, the liquid polymeric being disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate so that the liquid polymeric material flows towards the edges of the first substrate and the second substrate; and

curing the liquid polymeric material,

wherein said conducting surface of said first planar substrate includes first conductive pads, and said conducting surface of said second planar substrate includes second conductive pads and solder bumps disposed on said second conductive pads,

wherein said solder bumps comprise a solder material fluxing agent,

wherein said liquid polymeric material comprises a polymer fluxing agent,

wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid, and

wherein said beta phenylacid comprises beta phenylacrylic acid and said beta phenylhydroxyacid comprises beta phenylhydroxyacrylic acid.

Claim 15 (previously presented): A method for producing an assembly of substrates comprising:

dispensing a liquid polymeric material on one of a conducting surface on a first substantially planar substrate and a conducting surface on a second substantially planar substrate, the liquid polymeric being disposed inwardly from the edges of the first and the second substrate;

pressing the liquid polymeric material between the first and the second substrate so that the liquid polymeric material flows towards the edges of the first substrate and the second substrate; and

curing the liquid polymeric material,

wherein said conducting surface of said first planar substrate includes first conductive pads, and said conducting surface of said second planar substrate includes second conductive pads and solder bumps disposed on said second conductive pads,

wherein said solder bumps includes no solder material fluxing agent and said liquid polymeric material comprises a polymer fluxing agent,

wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta phenylhydroxyacid, and

wherein said beta phenylacid comprises beta phenylacrylic acid and said beta phenylhydroxyacid comprises beta phenylhydroxyacrylic acid.

Claim 16 (original): The method of Claim 1 wherein said liquid polymeric material comprises from about 15% by weight to about 70% by weight of a polymeric resin, from about 15% by weight to about 70% by weight of a curing agent, and from about 0.10% by weight to about 20% by weight of a fluxing agent.

Claim 17 – 20 (canceled).

Claim 21 (previously presented): The method of claim 1 wherein at least a portion of the step of curing said liquid polymeric material after said solder joint has been formed is performed at a temperature which is lower than the melting point of said solder.

Claim 22 (previously presented): The method of claim 21 wherein the step of forming a conductive joint is performed at a temperature in the range of about 200° C to about 240° C, and said lower curing temperature is in the range of about 100° C to about 180° C.

Claim 23 (previously presented): The method of claim 1 wherein the liquid polymeric material is dispensed at multiple points.

Claim 24 (previously presented): The method of claim 8 wherein said polymer fluxing agent retards the curing time of the polymer.

Claim 25 (previously presented): The method of claim 1 wherein said method is performed in a vacuum.

Claim 26 (previously presented): The method of claim 1 wherein said liquid polymer contains no metallic or conductive particles.